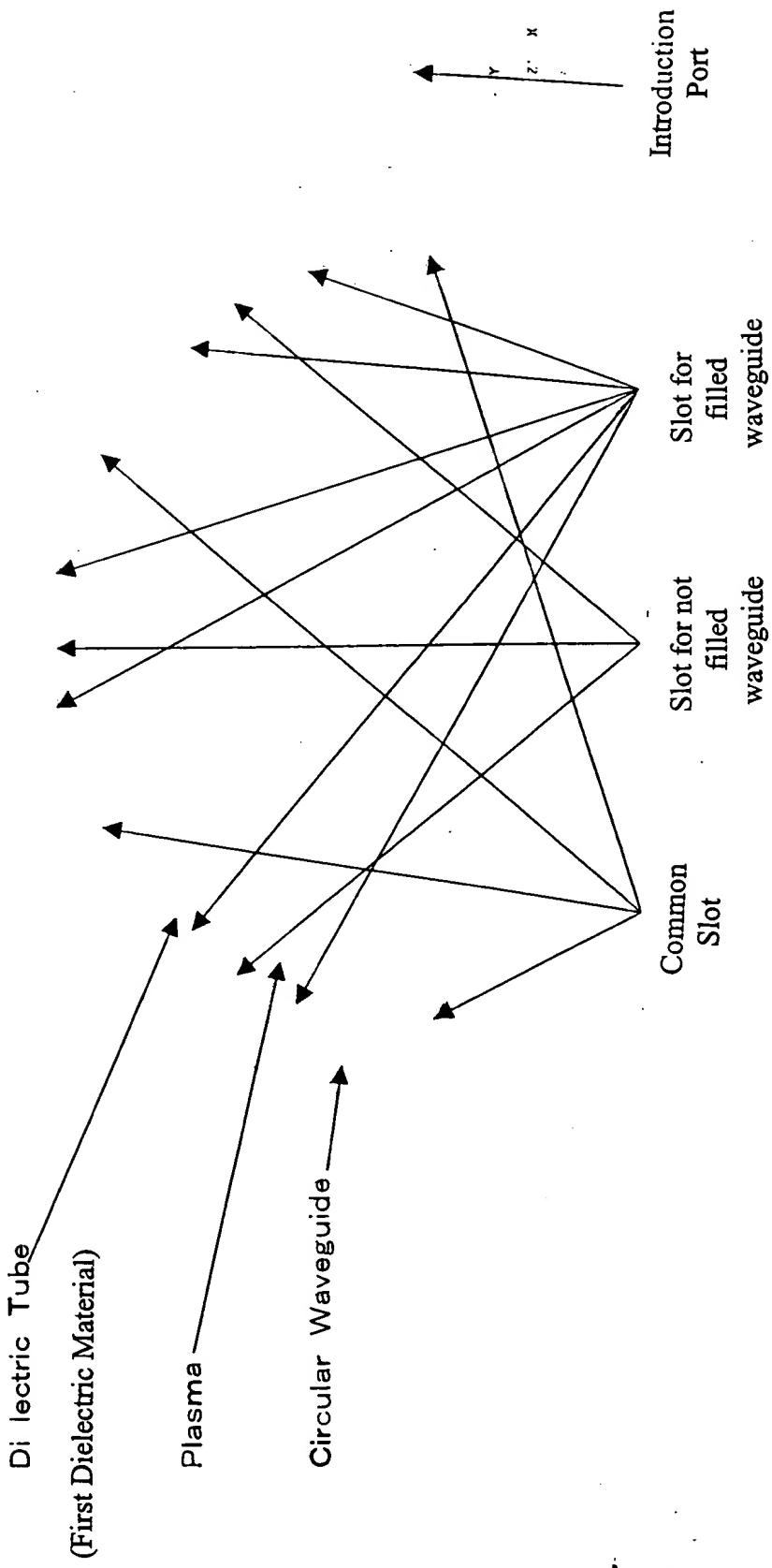




## Structure of CMA for Simulation for Comparing Absence/Presence of Second Dielectric Material

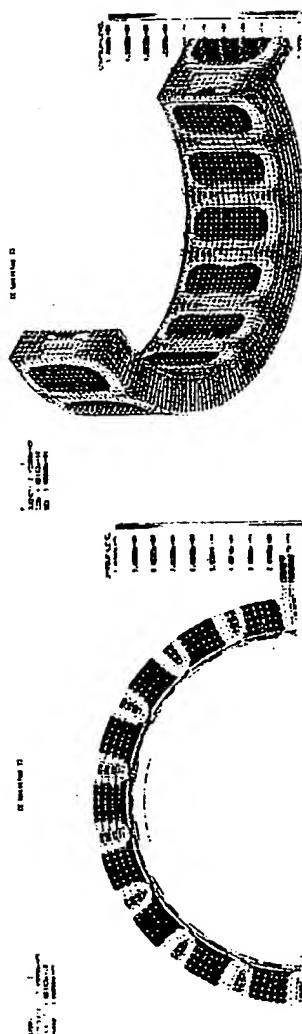
Figure A:

TOTAL NODE : 13380  
TOTAL ELEMENT : 10380



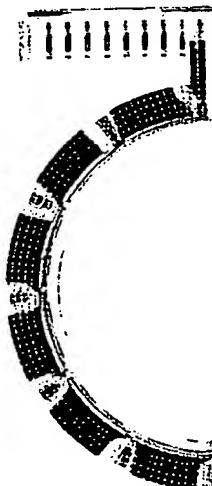
O I P A  
NOV 25 2002  
U.S. PATENT & TRADEMARK OFFICE WASH.  
Microwave Electric Field Distribution  
(Under Absence/Presence of Second  
Dielectric Material)

Filled with Dielectric

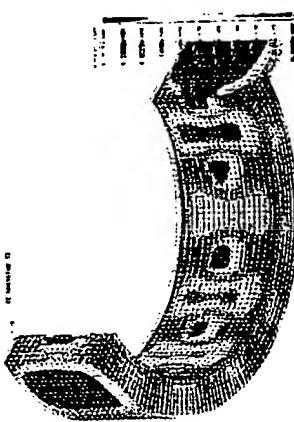


Top View

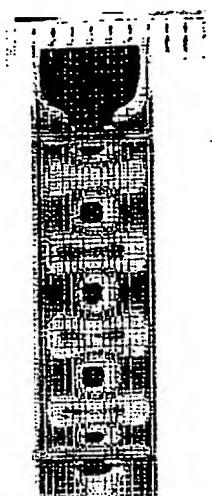
Not Filled



Oblique View



Inner Side View



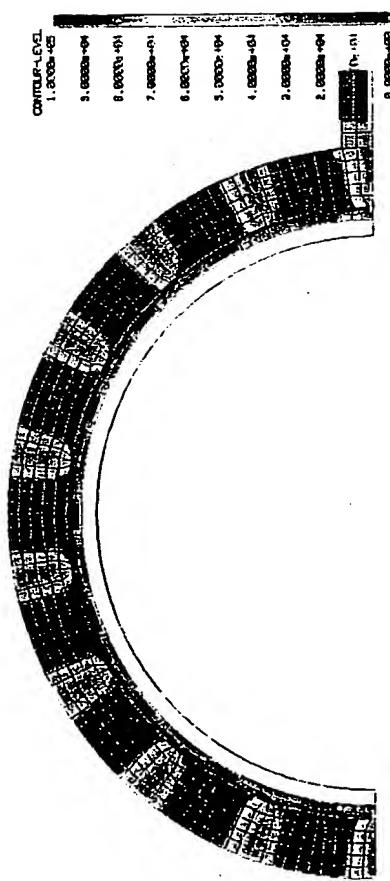


Filled with Dielectric

Top View

STEP:  
PROJECTION: 2.40000e+00  
PROTRUSION: 4.00000e-16  
PHASE: 3.00000e+00

(C) UNIT 111 (ed. 1)



Electric field distribution: node 16  
Hyp: 1.33333e-00  
Ref. B: 1.118

STEP:  
PROJECTION: 2.40000e+00  
PROTRUSION: 4.00000e-16  
PHASE: 1.00000e+00

(C) UNIT 111 (ed. 1)

Not Filled



Oblique View

Filled with Dielectric

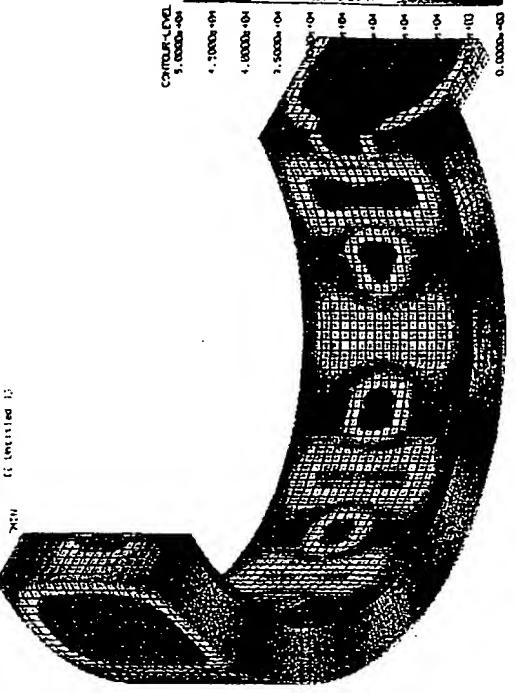
(C: Untitled 1)

STEP:  
PRODUCT: 2.  
POSITION: 4.08115E-10  
PITCH: 3.00000E+01

(C: Untitled 1)

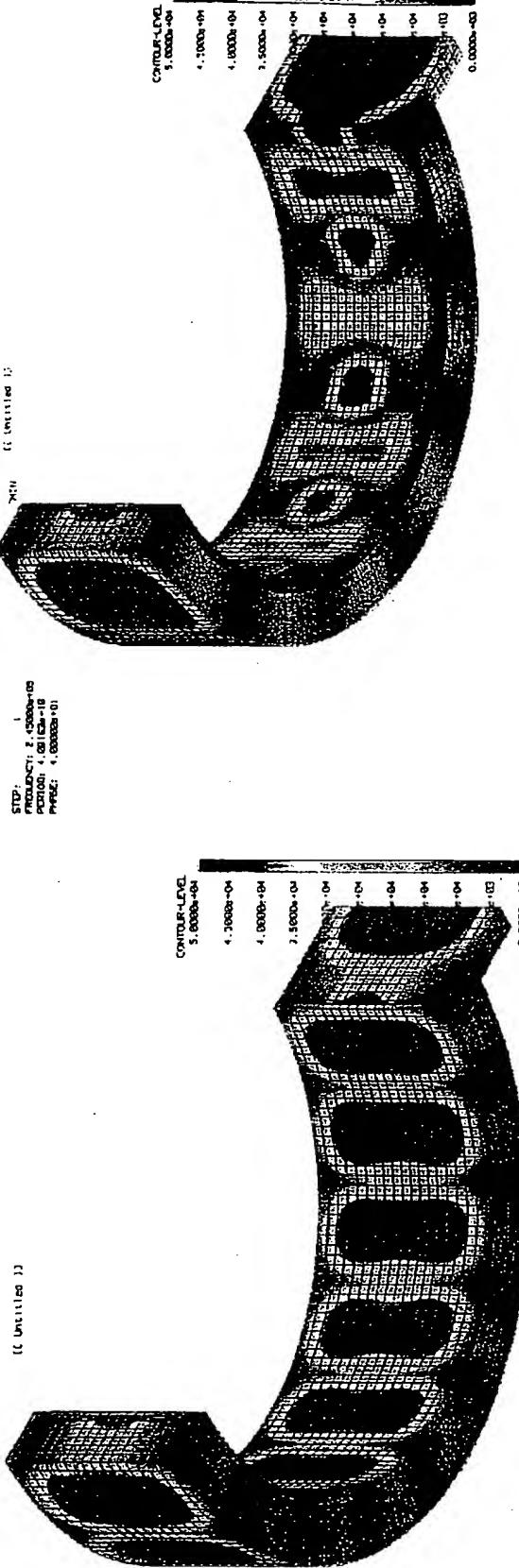
STEP:  
PRODUCT: 1.  
POSITION: 4.08115E-10  
PITCH: 3.00000E+01

(C: Untitled 1)



ELECTRIC FIELD AMPLITUDE X:  
HIGH: 1.3373E+02 VDE: 2125  
LOW: 1.3300E+02 VDE: 1116 X

ELECTRIC FIELD AMPLITUDE Y:  
HIGH: 1.3373E+02 VDE: 2125  
LOW: 1.3300E+02 VDE: 1116





### Filled with Dielectric

STP:  
1  
PRODUCTCY: 2.19300e-09  
PERIOD: 4.68152e-10  
PERC: 3.00000e-01

[CC Unfilled ]

### Inner Side View

Not Filled

[CC Unfilled ]

STP:  
1  
2.19300e-09  
1.68152e-10  
1.00000e-01

